

# System-in-Package (SiP) Solutions

Semiconductor companies are continually faced with complex integration challenges as consumers want their electronics to be smaller, faster and higher performance with more and more functionality packed into a single device. This

## Advantages of SiP



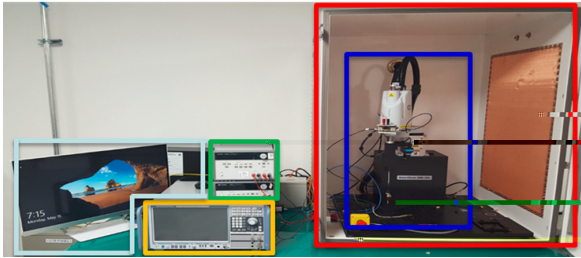




## Test Services

To meet the need for increased integration, improved electrical performance, reduced power consumption, faster speed and smaller device sizes, several advantages are driving the industry towards SiP solutions including:

- » Experience in RF ATE mass production on Advantest RF (< 6 GHz), Teradyne RF system (< 6GHz), LTX-CX (< 6 GHz) and NI-PXI (<6 GHz) platform, utilizing multiple sites (up to 16 sites)
- » Capability on Microwave option (GEN4/UltraWave12G) for Catalyst/IFLEX/uFLEX (Teradyne RF)
- » Experience in RF mass production volume test and multiple sites (up to 16 sites and 600M units over the past 5 years)
- » Proven RF Test Development Engineering on 60GHz Transceiver, GPS, RFFE Envelope Tracker, etc.
- » EMI and Electromagnetic Susceptibility (EMS) measurement and characterization capabilities, including near field testing



EMI and EMS Measurement

## Full Turnkey Solutions

We look forward to working with you to serve your complex system integration needs. Our industry leading advanced capabilities, from design to assembly and test, and multiple assembly platforms (laminated, eWLB and wirebond), along with our flexible business model, high throughput and high yield automated processes enable us to deliver diverse solutions for our customer base.

As demand for complex, highly integrated electronics devices continues to grow and evolve in the semiconductor industry, you can rely on our advanced technology and manufacturing experience to deliver the optimum SiP solution for your competitive integration needs.



SiP Assembly